10/008,665

L Number	Hits	Search Text	DB	Time stamp
-	· 6 ·	5156729.pn. 4108739.pn.	USPAT;	2003/04/16
		·	US-PGPUB;	09:03
			EPO; JPO;	
			DERWENT	
-	23	205/102,104,157,170,176,182.ccls. and ((single or one)	USPAT;	2003/04/16
		adj bath)	US-PGPUB;	09:11
			EPO; JPO;	
			DERWENT	
-	5	("3770571" "4487654" "4652348" "5052103"	USPAT	2003/04/16
		"5320719").PN.		09:10
-	203	205/102,104,157,170,176,182.ccls. and (laminate or	USPAT;	2003/04/16
		laminated or laminar or multilayered or multilayer or	US-PGPUB;	09:13
		modulated)	EPO; JPO;	03.10
		,	DERWENT	
_	114	205/102,104,157,170,176,182.ccls. and (multilayered	USPAT;	2003/04/16
		or multilayer or modulated)	US-PGPUB;	09:29
			EPO; JPO;	
			DERWENT	
-	1	205/102,104,157,170,176,182.ccls. and ((compositional	USPAT;	2003/04/16
İ		or structural) adj modulation)	US-PGPUB;	09:39
		or on derarally adjunerally	EPO; JPO;	07.37
			DERWENT	
_	1543	205/102,104,157,170,176,182.ccls.	USPAT;	2003/04/16
	10 10	2007102,101,107,170,170,102.0013.	US-PGPUB;	10:49
			EPO; JPO;	10.47
			DERWENT	
_	35	205/102,104,157,170,176,182.ccls. and	USPAT;	2003/04/16
		(semiconductor and (printed adj (circuit or wiring) adj	US-PGPUB;	10:56
		board))	EPO; JPO;	10.50
			DERWENT	
_	О	419881.apn.	USPAT;	2003/04/16
		115001.apri.	US-PGPUB;	10:51
			EPO; JPO;	10.51
			DERWENT	
_	4	"6309528"	USPAT;	2003/04/16
	'	000/320	US-PGPUB;	10:53
·			EPO; JPO;	10.55
			DERWENT	
_	3	205/\$.ccls. and taylor.in. and inman.in. and sun.in.	USPAT;	2003/04/16
	3	2007 4.0013. and raylor, in, and minun, in, and sun, in,	US-PGPUB;	10:53
			EPO; JPO;	10.33
			DERWENT	
_	15	205/102,104,157,170,176,182.ccls. and	USPAT;	2003/04/16
	1.5	(semiconductor with (printed adj (circuit or wiring)	US-PGPUB;	11:04
		adj board))	EPO; JPO;	11.04
		aa, 50a a <i>))</i>	DERWENT	
_	344	205/157.ccls.		2002/04/1/
	344	200/10/,005.	USPAT;	2003/04/16
			US-PGPUB;	11:25
			EPO; JPO;	
			DERWENT	

-	1341	205/157,170,176,182.ccls.	USPAT;	2003/04/16
			US-PGPUB;	11:27
			EPO; JPO;	••••
			DERWENT	
-	113	205/157,170,176,182.ccls. and (multilayer or	USPAT;	2003/04/16
		multilayered or (multiple adj layer))	US-PGPUB;	11:28
			EPO; JPO;	
			DERWENT	
-	39	(205/157,170,176,182.ccls. and (multilayer or	USPAT;	2003/04/16 11:51
		multilayered or (multiple adj layer))) and tin	US-PGPUB;	
			EPO; JPO;	
			DERWENT	
-	· 3	((205/157,170,176,182.ccls. and (multilayer or	USPAT;	2003/04/16
		multilayered or (multiple adj layer))) and tin) and	US-PGPUB;	11:52
		friction	EPO; JPO;	
		·	DERWENT	
-	71	205/157,170,176,182.ccls. and (multichip or "multi	USPAT;	2003/04/16
		chip" or capacitor or resistor)	US-PGPUB;	12:58
			EPO; JPO;	
			DERWENT	
-	53	205/157,170,176,182.ccls. and ((multichip or "multi	USPAT;	2003/04/16
		chip" or capacitor or resistor) and (printed or	US-PGPUB;	12:58
		semiconductor))	EPO; JPO;	
			DERWENT	
-	24	205/157,170,176,182.ccls. and ((multichip or "multi	USPAT;	2003/04/16
		chip" or capacitor or resistor) with (printed or	US-PGPUB;	12:58
		semiconductor))	EPO; JPO;	
			DERWENT	

L Number	Hits	Search Text	DB	Time stamp
37	1412	205/238,239,240,241,242,252,261,263,265,271,281,2	91J36DA805.ccls.	2003/04/16
				14:03
38	125	205/238,239,240,241,242,252,261,263,265,271,281,2	911 360 4805.ccls.	2003/04/16
		and (((wiring or circuit) adj board) or semiconductor)		14:03
39	22	(205/238,239,240,241,242,252,261,263,265,271,281,2	91,/3000,305.ccls	. 2003/04/16
		and (((wiring or circuit) adj board) or semiconductor))		14:04
		and (((multiple or multi) adj layer) or multilayer or		
40	1	((aDff4286,a)9,240,241,242,252,261,263,265,271,281,	2911, 310:0 1305.ccl	s.2003/04/16
		and (((wiring or circuit) adj board) or semiconductor))		14:05
		and (((multiple or multi) adj layer) or multilayer or		
41	3	((aDII/4288; a))9484 (p248; 2242)4852/2)61,263,265,271,281,	29 1,300 07305.ccl	s.2003/04/16
		and (((wiring or circuit) adj board) or semiconductor))		14:05
		and (((multiple or multi) adj layer) or multilayer or		
		multilayered)) and (pulse or pulsed or modulated)		
42	412	205/102,104,157,170,176,182.ccls. and	USPAT;	2003/04/16 14:11
	•	(semiconductor or ((wiring or circuit) adj board))	US-PGPUB;	
			EPO; JPO;	
			DERWENT	
43	101	(205/102,104,157,170,176,182.ccls. and	USPAT;	2003/04/16 14:11
		(semiconductor or ((wiring or circuit) adj board))) and	US-PGPUB;	
		(pulse or pulsed or modulated)	EPO; JPO;	
			DERWENT	
44	82	((205/102,104,157,170,176,182.ccls. and	USPAT;	2003/04/16
		(semiconductor or ((wiring or circuit) adj board))) and	US-PGPUB;	14:12
		(pulse or pulsed or modulated)) and copper	EPO; JPO;	
			DERWENT	
45	32	((205/102,104,157,170,176,182.ccls. and	USPAT;	2003/04/16
		(semiconductor or ((wiring or circuit) adj board))) and	US-PGPUB;	14:12
		(pulse or pulsed or modulated)) and tin	EPO; JPO;	
		W	DERWENT	
46	56	((205/102,104,157,170,176,182.ccls. and	USPAT;	2003/04/16
		(semiconductor or ((wiring or circuit) adj board))) and	US-PGPUB;	14:12
		(pulse or pulsed or modulated)) and potential	EPO; JPO;	
4.7	_	//205 //20 /0 / /55 /50 /5	DERWENT	
47	5	((205/102,104,157,170,176,182.ccls. and	USPAT;	2003/04/16
		(semiconductor or ((wiring or circuit) adj board))) and	US-PGPUB;	14:12
	Ì	(pulse or pulsed or modulated)) and (reduction adj	EPO; JPO;	
		potential)	DERWENT	